



Material Content Data Sheet



Sales Product Name		SAF-XC836-2FRI AB		Issued		20. July 2018		
MA#		MA001340694						
Package		PG-TSSOP-28-1		Weight*		107.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.495	4.20	4.20	41960	41960
leadframe	non noble metal	nickel	7440-02-0	14.398	13.44		134392	
	non noble metal	iron	7439-89-6	19.882	18.56	32.00	185589	319981
wire	noble metal	gold	7440-57-5	0.584	0.55	0.55	5451	5451
encapsulation	organic material	carbon black	1333-86-4	0.190	0.18		1776	
	plastics	epoxy resin	-	8.055	7.52		75187	
	inorganic material	silicondioxide	60676-86-0	55.179	51.49	59.19	515059	592022
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14370	14370
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13214	13214
glue	plastics	acrylic resin	-	0.279	0.26		2600	
	noble metal	silver	7440-22-4	1.114	1.04	1.30	10402	13002
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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